

Thermal Resistance

Parameter	Symbol	Value	Unit
Channel - soldering point ¹⁾	R_{thchs}	≤ 370	K/W

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Drain-source breakdown voltage $I_D = 650 \mu\text{A}$, $V_{G1S} = 0$, $V_{G2S} = 0$	$V_{(BR)DS}$	12	-	-	V
Gate1-source breakdown voltage $+I_{G1S} = 10 \text{ mA}$, $V_{G2S} = 0$, $V_{DS} = 0$	$+V_{(BR)G1SS}$	8	-	12	
Gate2 source breakdown voltage $\pm I_{G2S} = 10 \text{ mA}$, $V_{G1S} = 0$, $V_{DS} = 0$	$\pm V_{(BR)G2SS}$	8	-	13	
Gate1-source leakage current $V_{G1S} = 6 \text{ V}$, $V_{G2S} = 0$	$+I_{G1SS}$	-	100	-	μA
Gate 2 source leakage current $\pm V_{G2S} = 8 \text{ V}$, $V_{G1S} = 0$, $V_{DS} = 0$	$\pm I_{G2SS}$	-	-	50	nA
Drain current $V_{DS} = 5 \text{ V}$, $V_{G1S} = 0$, $V_{G2S} = 4 \text{ V}$	I_{DSS}	-	-	800	μA
Operating current (selfbiased) $V_{DS} = 5 \text{ V}$, $V_{G2S} = 4 \text{ V}$	I_{DSO}	8	13	16	mA
Gate2-source pinch-off voltage $V_{DS} = 5 \text{ V}$, $I_D = 100 \mu\text{A}$	$V_{G2S(p)}$	-	1	-	V

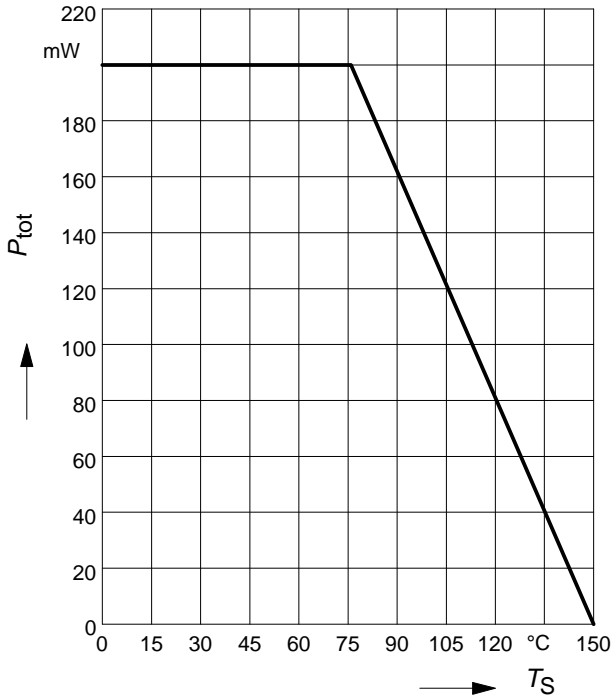
¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

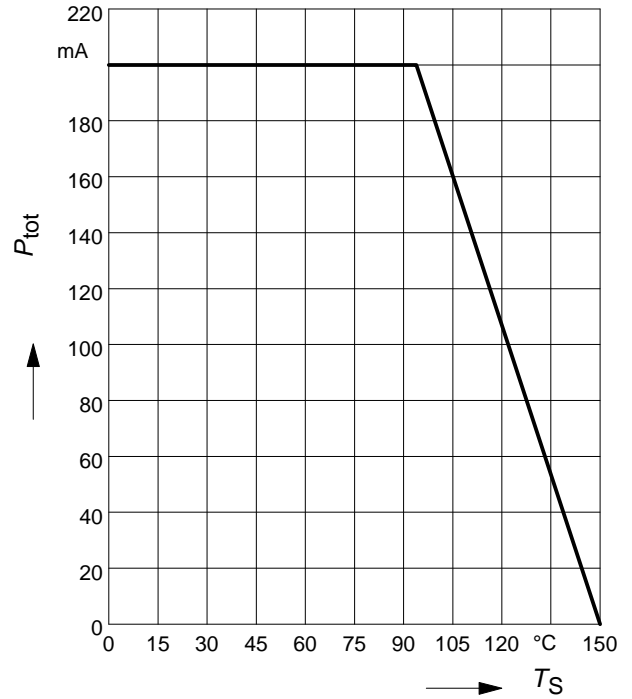
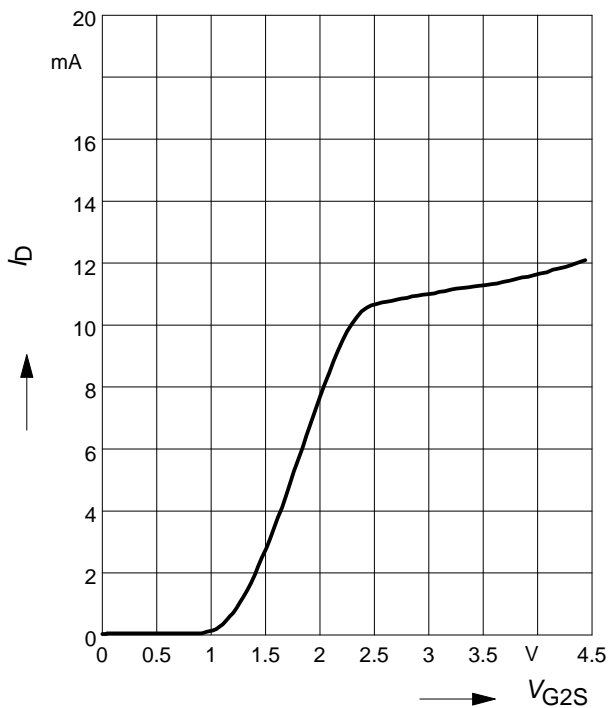
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Forward transconductance $V_{DS} = 5\text{ V}, V_{G2S} = 4.5\text{ V}$	g_{fs}	26	30	-	mS
Gate1 input capacitance $V_{DS} = 5\text{ V}, V_{G2S} = 4\text{ V}, f = 1\text{ MHz}$	C_{g1ss}	-	2.4	2.7	pF
Output capacitance $V_{DS} = 5\text{ V}, V_{G2S} = 4\text{ V}, f = 100\text{ MHz}$	C_{dss}	-	1.3	-	
Power gain (self biased) $V_{DS} = 5\text{ V}, V_{G2S} = 4\text{ V}, f = 800\text{ MHz}$	G_p	20	22	-	dB
Noise figure $V_{DS} = 5\text{ V}, V_{G2S} = 4\text{ V}, f = 800\text{ MHz}$	F	-	1.6	2.1	dB
Gain control range $V_{DS} = 5\text{ V}, V_{G2S} = 4\text{ V} \dots 0\text{ V}, f = 800\text{ MHz}$	ΔG_p	40	50	-	

Total power dissipation $P_{\text{tot}} = f(T_S)$

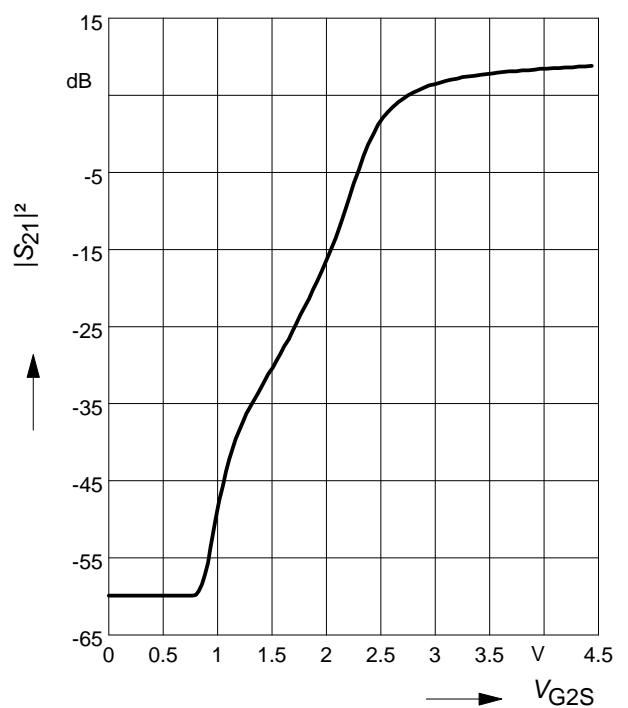
BF1005S, BF1005SR


Total power dissipation $P_{\text{tot}} = f(T_S)$

BF1005SW

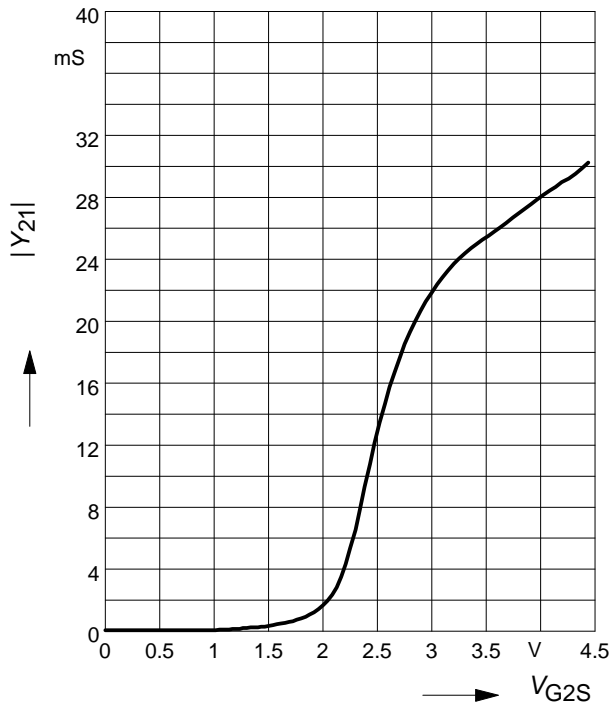

Drain current $I_D = f(V_{G2S})$

Insertion power gain

$$|S_{21}|^2 = f(V_{G2S})$$

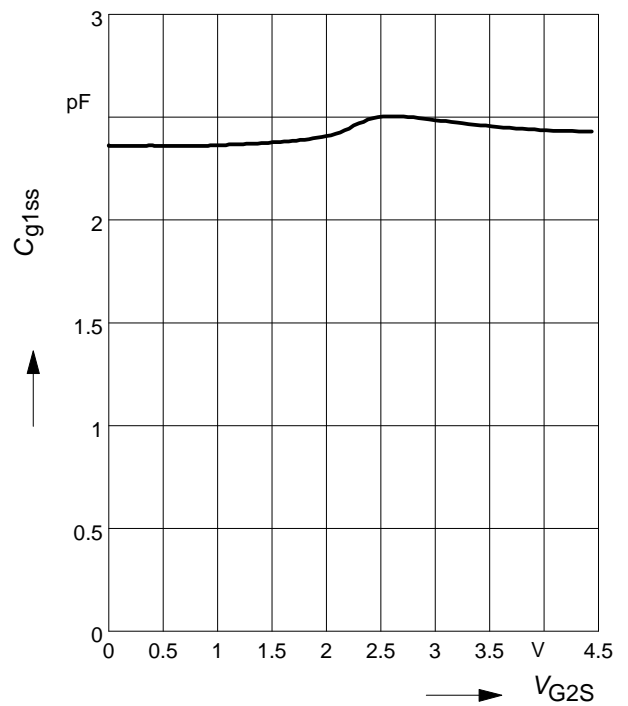


Forward transfer admittance

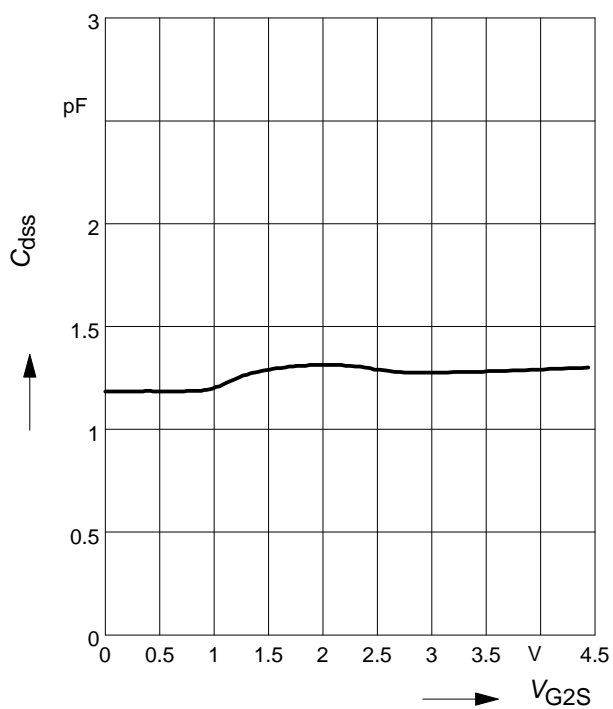
$$|Y_{21}| = f(V_{G2S})$$


Gate 1 input capacitance $C_{g1ss} = f(V_{G2S})$

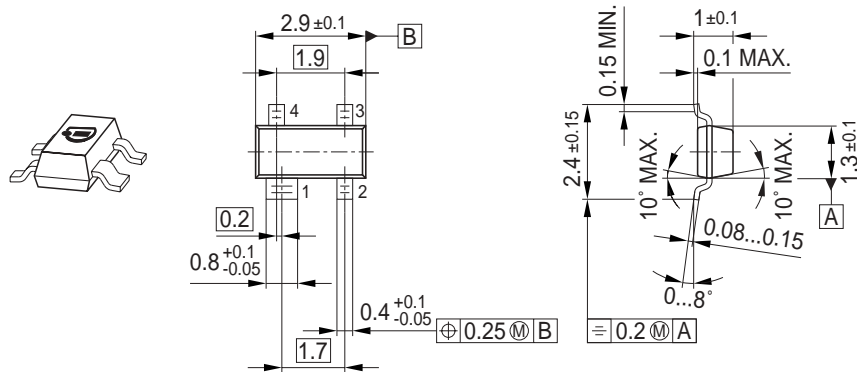
$$f = 200\text{MHz}$$


Output capacitance $C_{dss} = f(V_{G2S})$

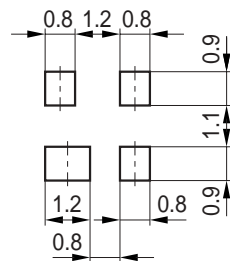
$$f = 200\text{MHz}$$



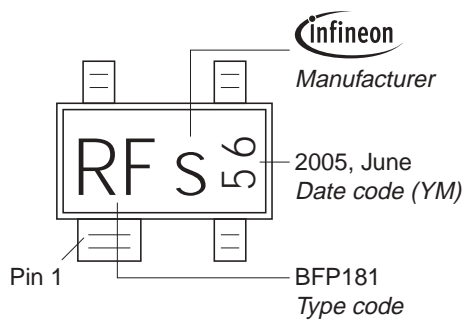
Package Outline



Foot Print

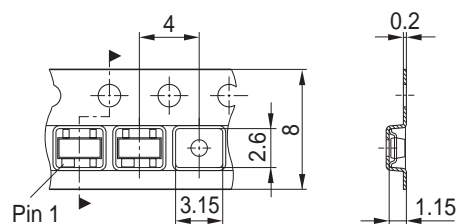


Marking Layout (Example)

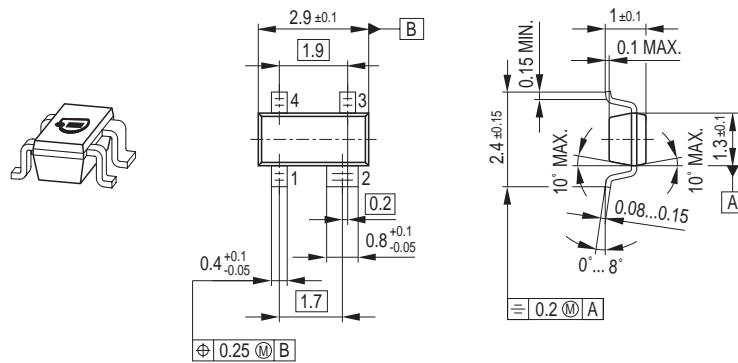


Standard Packing

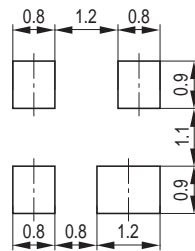
Reel $\varnothing 180 \text{ mm} = 3.000 \text{ Pieces/Reel}$
 Reel $\varnothing 330 \text{ mm} = 10.000 \text{ Pieces/Reel}$



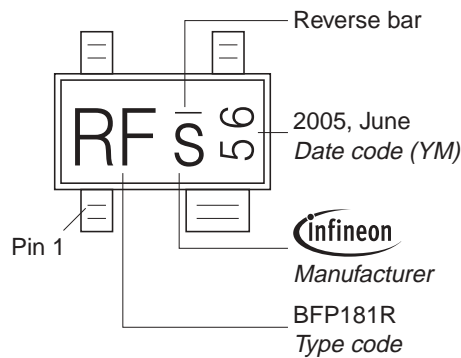
Package Outline



Foot Print

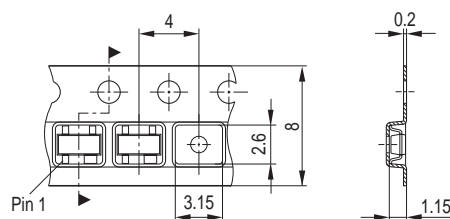


Marking Layout (Example)



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



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